

Jan Vanfleteren

List of Publications by Year in Descending Order

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The third column is the impact factor (IF) of the journal, and the fourth column is the number of citations of the article.

170
papers

3,642
citations

31
h-index

54
g-index

202
ext. papers

4,258
ext. citations

2.9
avg, IF

5.17
L-index

#	Paper	IF	Citations
170	Technological development for the reduction of out-of-plane deformation of metallic meander structures in thermoformed electronics. <i>International Journal of Advanced Manufacturing Technology</i> , 2022 , 119, 6649	3.2	0
169	Over-molding of flexible polyimide-based electronic circuits. <i>Flexible and Printed Electronics</i> , 2021 , 6, 025007	3.1	2
168	Fully Integrated Flexible Dielectric Monitoring Sensor System for Real-Time In Situ Prediction of the Degree of Cure and Glass Transition Temperature of an Epoxy Resin. <i>IEEE Transactions on Instrumentation and Measurement</i> , 2021 , 70, 1-9	5.2	3
167	Technological Challenges in the Development of Optogenetic Closed-Loop Therapy Approaches in Epilepsy and Related Network Disorders of the Brain. <i>Micromachines</i> , 2020 , 12,	3.3	3
166	Flexible Microsystems Using Over-molding Technology. <i>Procedia Manufacturing</i> , 2020 , 52, 26-31	1.5	1
165	Development and Washing Reliability Testing of a Stretchable Circuit on Knit Fabric. <i>Applied Sciences (Switzerland)</i> , 2020 , 10, 9057	2.6	2
164	Numerical simulation of a multi-inlet microfluidic device for biosensing purposes in osteoporosis management. <i>Journal of Diabetes and Metabolic Disorders</i> , 2019 , 18, 341-348	2.5	1
163	Stretchable Mold Interconnect Optimization: Peeling Automation and Carrierless Techniques. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2019 , 9, 955-962	1.7	1
162	Design Automation of Meandered Interconnects for Stretchable Circuits. <i>IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems</i> , 2019 , 38, 1648-1660	2.5	4
161	2019 ,		3
160	. <i>IEEE Transactions on Antennas and Propagation</i> , 2018 , 66, 2199-2209	4.9	25
159	Multifunctional and miniaturized flexible sensor patch: Design and application for in situ monitoring of epoxy polymerization. <i>Sensors and Actuators B: Chemical</i> , 2018 , 261, 144-152	8.5	25
158	2.5/3D dynamically stretchable and permanently shaped electronic circuits. <i>Microsystem Technologies</i> , 2018 , 24, 831-853	1.7	8
157	Design and Integration of Flexible Sensor Matrix for in Situ Monitoring of Polymer Composites. <i>ACS Sensors</i> , 2018 , 3, 1698-1705	9.2	18
156	From Fibrils to Toughness: Multi-Scale Mechanics of Fibrillating Interfaces in Stretchable Electronics. <i>Materials</i> , 2018 , 11,	3.5	4
155	Microphysiological flux balance platform unravels the dynamics of drug induced steatosis. <i>Lab on A Chip</i> , 2018 , 18, 2510-2522	7.2	18
154	2018 ,		2

153	Stretchability-The Metric for Stretchable Electrical Interconnects. <i>Micromachines</i> , 2018 , 9,	3.3	4
152	3D Multifunctional Composites Based on Large-Area Stretchable Circuit with Thermoforming Technology. <i>Advanced Electronic Materials</i> , 2018 , 4, 1800071	6.4	19
151	Arbitrarily Shaped 2.5D Circuits using Stretchable Interconnects Embedded in Thermoplastic Polymers . <i>Advanced Engineering Materials</i> , 2017 , 19, 1700032	3.5	28
150	Stretchable Electronic Platform for Soft and Smart Contact Lens Applications. <i>Advanced Materials Technologies</i> , 2017 , 2, 1700073	6.8	34
149	An Electrochemical Biosensor Based on AuNP-Modified Gold Electrodes for Selective Determination of Serum Levels of Osteocalcin. <i>IEEE Sensors Journal</i> , 2017 , 17, 3367-3374	4	15
148	A highly sensitive electrochemical biosensor based on AuNP-modified gold electrodes for selective determination of serum levels of crosslaps. <i>3 Biotech</i> , 2017 , 7, 312	2.8	3
147	Fabrication and Verification of Conjugated AuNP-Antibody Nanoprobe for Sensitivity Improvement in Electrochemical Biosensors. <i>Scientific Reports</i> , 2017 , 7, 16070	4.9	20
146	Rapid prototyping of microfluidic chips using laser-cut double-sided tape for electrochemical biosensors. <i>Journal of the Brazilian Society of Mechanical Sciences and Engineering</i> , 2017 , 39, 1469-1477	2	9
145	A Multiplexed Microfluidic Platform for Bone Marker Measurement: A Proof-of-Concept. <i>Micromachines</i> , 2017 , 8, 133	3.3	10
144	49-2: Invited Paper: Stretchable Passive Matrix LED Display with Thin-Film Based Interconnects. <i>Digest of Technical Papers SID International Symposium</i> , 2016 , 47, 664-667	0.5	6
143	Wearable Flexible Lightweight Modular RFID Tag With Integrated Energy Harvester. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2016 , 64, 2304-2314	4.1	34
142	Bone biosensors: knowing the present and predicting the future. <i>Journal of Micromechanics and Microengineering</i> , 2016 , 26, 023002	2	7
141	Facile fabrication of stretchable Ag nanowire/polyurethane electrodes using high intensity pulsed light. <i>Nano Research</i> , 2016 , 9, 401-414	10	113
140	Arbitrarily Shaped Rigid and Smart Objects Using Stretchable Interconnections. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2016 , 6, 533-544	1.7	8
139	Design and fabrication of a flexible dielectric sensor system for in situ and real-time production monitoring of glass fibre reinforced composites. <i>Sensors and Actuators A: Physical</i> , 2016 , 243, 103-110	3.9	29
138	Threefold Rotationally Symmetric SIW Antenna Array for Ultra-Short-Range MIMO Communication. <i>IEEE Transactions on Antennas and Propagation</i> , 2016 , 64, 1689-1699	4.9	21
137	Fabrication of 3-dimensional biodegradable microfluidic environments for tissue engineering applications. <i>Materials and Design</i> , 2016 , 89, 1315-1324	8.1	12
136	RTM Production Monitoring of the A380 Hinge Arm Droop Nose Mechanism: A Multi-Sensor Approach. <i>Sensors</i> , 2016 , 16,	3.8	13

135	Design and fabrication of a shielded interdigital sensor for noninvasive In situ real-time production monitoring of polymers. <i>Journal of Polymer Science, Part B: Polymer Physics</i> , 2016 , 54, 2028-2037	2.6	11
134	A new technology for rigid 3D free-form electronics based on the thermoplastic deformation of flat standard PCB type circuits 2016 ,		8
133	One-time deformable thermoplastic devices based on flexible circuit board technology 2016 ,		5
132	Real-time monitoring of metabolic function in liver-on-chip microdevices tracks the dynamics of mitochondrial dysfunction. <i>Proceedings of the National Academy of Sciences of the United States of America</i> , 2016 , 113, E2231-40	11.5	166
131	Poly(polyol sebacate) Elastomers as Coatings for Metallic Coronary Stents. <i>Macromolecular Bioscience</i> , 2016 , 16, 1678-1692	5.5	4
130	Flexible and stretchable electronics for wearable health devices. <i>Solid-State Electronics</i> , 2015 , 113, 116-120		76
129	Surface modification of an epoxy resin with polyamines and polydopamine: Adhesion toward electroless deposited copper. <i>Applied Surface Science</i> , 2015 , 353, 238-244	6.7	22
128	Impact of geometry on stretchable meandered interconnect uniaxial tensile extension fatigue reliability. <i>Microelectronics Reliability</i> , 2015 , 55, 143-154	1.2	21
127	Free-form 2.5D thermoplastic circuits using one-time stretchable interconnections. <i>Materials Research Society Symposia Proceedings</i> , 2015 , 1798, 1		3
126	Deformable Microsystem for In Situ Cure Degree Monitoring of GFRP (Glass Fiber Reinforced Plastic). <i>Materials Research Society Symposia Proceedings</i> , 2015 , 1798, 1		
125	9.4: Stretchable 45 [B0] RGB LED Display Using Meander Wiring Technology. <i>Digest of Technical Papers SID International Symposium</i> , 2015 , 46, 102-105	0.5	15
124	Applying QMSIW technique in textile for compact wearable design and high body-antenna isolation 2015 ,		1
123	2.5D Smart Objects Using Thermoplastic Stretchable Interconnects. <i>International Symposium on Microelectronics</i> , 2015 , 2015, 000868-000873	0.2	6
122	Non-destructive evaluation of an infusion process using capacitive sensing technique 2015 , 293-297		
121	High-Yield Fabrication Process for 3D-Stacked Ultrathin Chip Packages Using Photo-Definable Polyimide and Symmetry in Packages. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2014 , 4, 158-167	1.7	11
120	Flexible and stretchable electronics for wearable healthcare 2014 ,		9
119	Fabrication and functionalization of PCB gold electrodes suitable for DNA-based electrochemical sensing. <i>Bio-Medical Materials and Engineering</i> , 2014 , 24, 1705-14	1	8
118	Conformable, Low Level Light Therapy platform 2014 ,		5

117	Stretchable optical waveguides. <i>Optics Express</i> , 2014 , 22, 4168-79	3.3	71
116	Arbitrarily Shaped 2.5D Circuits Using Stretchable Interconnections and Embedding in Thermoplastic Polymers. <i>Procedia Technology</i> , 2014 , 15, 208-215		20
115	Development of a Dielectric Sensor System for the On-line Cure Monitoring of Composites. <i>Procedia Technology</i> , 2014 , 15, 631-637		15
114	Active textile antennas in professional garments for sensing, localisation and communication. <i>International Journal of Microwave and Wireless Technologies</i> , 2014 , 6, 331-341	0.8	12
113	Surface modification of an epoxy resin with polyamines and polydopamine: The effect on the initial electroless copper deposition. <i>Applied Surface Science</i> , 2014 , 305, 321-329	6.7	7
112	Surface characterization and stability of an epoxy resin surface modified with polyamines grafted on polydopamine. <i>Applied Surface Science</i> , 2014 , 303, 465-472	6.7	37
111	3-D Stacking of Ultrathin Chip Packages: An Innovative Packaging and Interconnection Technology. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2013 , 3, 1114-1122	1.7	4
110	PDMS Selective Bonding for the Fabrication of Biocompatible All Polymer NC Microvalves. <i>Journal of Microelectromechanical Systems</i> , 2013 , 22, 1354-1360	2.5	7
109	Reliability of a stretchable interconnect utilizing terminated, in-plane meandered copper conductor. <i>Microelectronics Reliability</i> , 2013 , 53, 956-963	1.2	22
108	A Wireless Sensor Network Protocol for an Inertial Motion Tracking System. <i>Wireless Personal Communications</i> , 2013 , 71, 1961-1975	1.9	
107	Self-aligned flat ultra-thin chip package for flexible circuits. <i>Circuit World</i> , 2013 , 39, 174-180	0.7	0
106	Stretchable Electronics Technology for Large Area Applications: Fabrication and Mechanical Characterization. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2013 , 3, 229-235	1.7	63
105	Stretchable Circuits with Horseshoe Shaped Conductors Embedded in Elastic Polymers. <i>Japanese Journal of Applied Physics</i> , 2013 , 52, 05DA18	1.4	32
104	A 3D printed dry electrode for ECG/EEG recording. <i>Sensors and Actuators A: Physical</i> , 2012 , 174, 96-102	3.9	143
103	Feasibility Study and Performance Analysis of a Gyroless Orientation Tracker. <i>IEEE Transactions on Instrumentation and Measurement</i> , 2012 , 61, 2274-2282	5.2	9
102	Fabrication and Characterization of Flexible Ultrathin Chip Package Using Photosensitive Polyimide. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2012 , 2, 1099-1106	1.7	20
101	Solution-processed and low-temperature metal oxide n-channel thin-film transistors and low-voltage complementary circuitry on large-area flexible polyimide foil. <i>Journal of the Society for Information Display</i> , 2012 , 20, 499-507	2.1	15
100	Adhesive bonding by SU-8 transfer for assembling microfluidic devices. <i>Microfluidics and Nanofluidics</i> , 2012 , 13, 987-991	2.8	10

99	Embedding thinned chips in flexible PCBs 2012 ,		3
98	An approach to produce a stack of photo definable polyimide based flat UTCs 2012 ,		3
97	Synchronizing Music and Movement with BeatLED: an Interactive Musical Social Game. <i>Journal of New Music Research</i> , 2012 , 41, 351-363	1.1	1
96	Modeling of Printed Circuit Board Inspired Stretchable Electronic Systems 2012 , 141-159		1
95	Reliability and Application Scenarios of Stretchable Electronics Realized Using Printed Circuit Board Technologies 2012 , 207-233		1
94	Two axis optoelectronic tactile shear stress sensor. <i>Sensors and Actuators A: Physical</i> , 2012 , 186, 63-68	3.9	10
93	Reliable stretchable gold interconnects in biocompatible elastomers. <i>Journal of Polymer Science, Part B: Polymer Physics</i> , 2012 , 50, 773-776	2.6	29
92	Fabrication of a biocompatible flexible electroosmosis micropump. <i>Microfluidics and Nanofluidics</i> , 2012 , 12, 771-777	2.8	10
91	Printed circuit board technology inspired stretchable circuits. <i>MRS Bulletin</i> , 2012 , 37, 254-260	3.2	111
90	Thin-film stretchable electronics technology based on meandering interconnections: fabrication and mechanical performance. <i>Journal of Micromechanics and Microengineering</i> , 2012 , 22, 015002	2	79
89	Stretchable biocompatible electronics by embedding electrical circuitry in biocompatible elastomers. <i>Annual International Conference of the IEEE Engineering in Medicine and Biology Society IEEE Engineering in Medicine and Biology Society Annual International Conference</i> , 2012 , 2012, 6007-10	0.9	2
88	Integration of stretchable and washable electronic modules for smart textile applications. <i>Journal of the Textile Institute</i> , 2012 , 103, 1127-1138	1.5	55
87	Influence of barrier absorption properties on laser patterning thin organic films 2012 ,		2
86	SCB and SMI: two stretchable circuit technologies, based on standard printed circuit board processes. <i>Circuit World</i> , 2012 , 38, 232-242	0.7	17
85	Thinned dies in a stretchable package 2012 ,		2
84	Ultra Thin Optical Tactile Shear Sensor. <i>Procedia Engineering</i> , 2011 , 25, 1393-1396		7
83	. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2011 , 1, 1319-1327	1.7	17
82	Design of an Implantable Slot Dipole Conformal Flexible Antenna for Biomedical Applications. <i>IEEE Transactions on Antennas and Propagation</i> , 2011 , 59, 3556-3564	4.9	126

81	Fabrication of an implantable stretchable electro-osmosis pump 2011 ,		3
80	Polyimide-Enhanced Stretchable Interconnects: Design, Fabrication, and Characterization. <i>IEEE Transactions on Electron Devices</i> , 2011 , 58, 2680-2688	2.9	77
79	In-body path loss models for implants in heterogeneous human tissues using implantable slot dipole conformal flexible antennas. <i>Eurasip Journal on Wireless Communications and Networking</i> , 2011 , 2011,	3.2	13
78	Design and implementation of flexible and stretchable systems. <i>Microelectronics Reliability</i> , 2011 , 51, 1069-1076	1.2	31
77	Shape-memory anchoring system for bladder sensors. <i>Journal of Biomedical Materials Research - Part B Applied Biomaterials</i> , 2011 , 96, 369-75	3.5	10
76	. <i>IEEE Photonics Technology Letters</i> , 2011 , 23, 771-773	2.2	31
75	The effects of encapsulation on deformation behavior and failure mechanisms of stretchable interconnects. <i>Thin Solid Films</i> , 2011 , 519, 2225-2234	2.2	57
74	Ultra-Thin Chip Package (UTCP) and stretchable circuit technologies for wearable ECG system. <i>Annual International Conference of the IEEE Engineering in Medicine and Biology Society IEEE Engineering in Medicine and Biology Society Annual International Conference</i> , 2011 , 2011, 6886-9	0.9	14
73	System-in-Foil Technology 2011 , 141-157		3
72	Improved Stretchable Electronics Technology for Large Area Applications. <i>Materials Research Society Symposia Proceedings</i> , 2010 , 1271, 1		7
71	Performance of a new type of module based on back-contact solar cells 2010 ,		2
70	Development of a thin-film stretchable electrical interconnection technology for biocompatible applications 2010 ,		1
69	Ultra-flexible and ultra-thin embedded medical devices on large area panels 2010 ,		7
68	Stretchable and Washable Electronics for Embedding in Textiles. <i>Materials Research Society Symposia Proceedings</i> , 2010 , 1271, 1		9
67	Design and analysis of a novel fine pitch and highly stretchable interconnect. <i>Microelectronics International</i> , 2010 , 27, 33-38	0.8	7
66	The effect of pitch on deformation behavior and the stretching-induced failure of a polymer-encapsulated stretchable circuit. <i>Journal of Micromechanics and Microengineering</i> , 2010 , 20, 075036	2	43
65	Highly Reliable Flexible Active Optical Links. <i>IEEE Photonics Technology Letters</i> , 2010 , 22, 287-289	2.2	35
64	Fine-Pitch Capabilities of the Flat Ultra-Thin Chip Packaging (UTCP) Technology. <i>IEEE Transactions on Advanced Packaging</i> , 2010 , 33, 72-78		10

63	. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2010 , 33, 754-760		46
62	Embedded flexible optical shear sensor 2010 ,		7
61	Thermo-mechanical analysis of flexible and stretchable systems 2010 ,		1
60	Reliability assessment of stretchable interconnects 2010 ,		8
59	A novel approach to embed off-chip RF passives in PCB based on thin film technology 2010 ,		1
58	High density optical pressure sensor foil based on arrays of crossing flexible waveguides 2010 ,		3
57	In vitro cytotoxicity testing and the application of elastic interconnection technology for short-term implantable electronics. <i>Annual International Conference of the IEEE Engineering in Medicine and Biology Society IEEE Engineering in Medicine and Biology Society Annual International Conference</i> , 2009 , 2009, 4880-3	0.9	2
56	Design of flexible, low-power and wireless sensor nodes for human posture tracking aiding epileptic seizure detection 2009 ,		9
55	In situ observations on deformation behavior and stretching-induced failure of fine pitch stretchable interconnect. <i>Journal of Materials Research</i> , 2009 , 24, 3573-3582	2.5	43
54	An array waveguide sensor for artificial optical skins 2009 ,		9
53	A Novel Interconnect Design with High Stretchability and Fine Pitch Capability for Applications in Stretchable Electronics. <i>Materials Research Society Symposia Proceedings</i> , 2009 , 1192, 27		2
52	Remote Atmospheric Pressure DC Glow Discharge Treatment for Adhesion Improvement of PDMS. <i>Plasma Processes and Polymers</i> , 2009 , 6, S406-S411	3.4	19
51	Design and implementation of advanced systems in a flexible-stretchable technology for biomedical applications. <i>Sensors and Actuators A: Physical</i> , 2009 , 156, 79-87	3.9	80
50	Improved passive-matrix multiplexability with a modular display and UTCP technology. <i>Displays</i> , 2009 , 30, 71-76	3.4	1
49	3D orientation tracking based on unscented Kalman filtering of accelerometer and magnetometer data 2009 ,		23
48	Design and fabrication of a low cost implantable bladder pressure monitor. <i>Annual International Conference of the IEEE Engineering in Medicine and Biology Society IEEE Engineering in Medicine and Biology Society Annual International Conference</i> , 2009 , 2009, 4864-7	0.9	16
47	Fabrication Processes for Embedding Thin Chips in Flat Flexible Substrates. <i>IEEE Transactions on Advanced Packaging</i> , 2009 , 32, 77-83		31
46	Design and performance of metal conductors for stretchable electronic circuits. <i>Circuit World</i> , 2009 , 35, 22-29	0.7	52

45	3D Integrated, Ultra-Thin Functional Microcontroller Device for Wireless, Flexible ECG Systems. <i>ECS Transactions</i> , 2009 , 18, 707-712	1	2
44	16.4: Ultra-Thin Chip Packaging (UTCP): A Promising Technology for Future Flexible Display Interconnection. <i>Digest of Technical Papers SID International Symposium</i> , 2009 , 40, 202	0.5	3
43	Assembly of ultra-thin chip packages (UTCPs) for enhanced flexibility of flexible displays 2008 ,		5
42	Design and Manufacturing of Stretchable High-Frequency Interconnects. <i>IEEE Transactions on Advanced Packaging</i> , 2008 , 31, 802-808		70
41	Active optical links embedded in flexible substrates 2008 ,		2
40	Multiple chip integration for flat flexible electronics 2008 ,		4
39	Design and performance of metal conductors for stretchable electronic circuits 2008 ,		4
38	Laser based fast prototyping methodology of producing stretchable and conformable electronic systems 2008 ,		13
37	Embedding and assembly of ultrathin chips in multilayer flex boards. <i>Circuit World</i> , 2008 , 34, 3-8	0.7	24
36	Design of metal interconnects for stretchable electronic circuits. <i>Microelectronics Reliability</i> , 2008 , 48, 825-832	1.2	296
35	Elastic and Conformable Electronic Circuits and Assemblies using MID in polymer 2007 ,		17
34	Adhesion enhancement by a dielectric barrier discharge of PDMS used for flexible and stretchable electronics. <i>Journal Physics D: Applied Physics</i> , 2007 , 40, 7392-7401	3	98
33	Flexible-substrate low-cost construction of a coplanar-waveguide aperture-coupled microstrip patch antenna. <i>Microwave and Optical Technology Letters</i> , 2007 , 49, 1071-1074	1.2	5
32	Biomedical stretchable systems using MID based stretchable electronics technology. <i>Annual International Conference of the IEEE Engineering in Medicine and Biology Society</i> , 2007 , 2007, 5688-91		6
31	Low cost, biocompatible elastic and conformable electronic technologies using MID in stretchable polymer. <i>Annual International Conference of the IEEE Engineering in Medicine and Biology Society</i> , 2007 , 2007, 6593-6		1
30	Design and Fabrication of Elastic Interconnections for Stretchable Electronic Circuits. <i>IEEE Electron Device Letters</i> , 2007 , 28, 552-554	4.4	185
29	2007 ,		16
28	Embedding of Optical Interconnections in Flexible Electronics 2007 ,		4

27	Stretchable electronic systems 2006 ,		18
26	Elastic Interconnects for Stretchable Electronic Circuits using MID (Moulded Interconnect Device) Technology. <i>Materials Research Society Symposia Proceedings</i> , 2006 , 926, 1		9
25	Technologies for highly miniaturized autonomous sensor networks. <i>Microelectronics Journal</i> , 2006 , 37, 1563-1568	1.8	38
24	Comparison of different flex materials in high density flip chip on flex applications. <i>Microelectronics Reliability</i> , 2003 , 43, 445-451	1.2	14
23	Cell gap optimization and alignment effects in reflective PDLC microdisplays. <i>Liquid Crystals</i> , 2001 , 28, 1245-1252	2.3	8
22	Method for measuring the cell gap in liquid-crystal displays. <i>Optical Engineering</i> , 2001 , 40, 259	1.1	13
21	Electro-conductive adhesives for high density package and flip-chip interconnections. <i>Microelectronics Reliability</i> , 2000 , 40, 1215-1226	1.2	45
20	Extension of a multilayer interconnection technology in MCM-Si with opto-electronic facilities. <i>Microelectronics Reliability</i> , 2000 , 40, 163-170	1.2	
19	A five-layer thin film MCM-Si design using oxynitride dielectrics. <i>Microelectronics International</i> , 1998 , 15, 39-42	0.8	
18	Analysis of transient photoconductivity in CdSe: Cu: Cl thin films. <i>Physica Status Solidi A</i> , 1994 , 142, 127-140		4
17	A polymer-network liquid-crystal poly-CdSe TFT active-matrix display. <i>Journal of the Society for Information Display</i> , 1993 , 1, 189	2.1	
16	Geometric design of lensless photoconductive contact-type image sensors. <i>Journal of the Society for Information Display</i> , 1993 , 1, 233	2.1	1
15	A lensless contact-type image sensor based on a CdSe photoconductive array. <i>Sensors and Actuators A: Physical</i> , 1993 , 37-38, 546-551	3.9	7
14	Thin film cadmium selenide technology in large area active matrix high resolution displays. <i>Microelectronic Engineering</i> , 1992 , 19, 187-190	2.5	10
13	CdSe-based thin-film integrated optical sensors. <i>Sensors and Actuators A: Physical</i> , 1992 , 32, 437-441	3.9	10
12	The electrical performance of a complementary CdSe:In/Ge:Cu thin film transistor technology for flat panel displays. <i>Solid-State Electronics</i> , 1991 , 34, 143-147	1.7	3
11	The influence of low copper doping concentrations on the recrystallization process in and the electrical properties of germanium in Ge:Cu thin film transistors. <i>Thin Solid Films</i> , 1990 , 189, 235-245	2.2	7
10	. <i>IEEE Transactions on Electron Devices</i> , 1990 , 37, 636-639	2.9	15

9	. <i>IEEE Journal of Solid-State Circuits</i> , 1990 , 25, 531-538	5.5	5
8	Polycrystalline CdSe films for thin film transistors. <i>Journal of Crystal Growth</i> , 1988 , 86, 924-928	1.6	58
7	On the field effect in polycrystalline CdSe thin-film transistors. <i>Journal of Applied Physics</i> , 1988 , 64, 3282-3286	2.3	23
6	A new technology for fast switching circuits on glass. <i>IEEE Electron Device Letters</i> , 1987 , 8, 477-479	4.4	6
5	A comparative study of evaporated Al ₂ O ₃ , SiO ₂ and SiO ₂ /Al ₂ O ₃ thin films. <i>Thin Solid Films</i> , 1986 , 139, 89-94	2.2	9
4	A four-vacuum-cycle lift-off process for the polycrystalline CdSe thin-film transistor. <i>IEEE Electron Device Letters</i> , 1985 , 6, 11-13	4.4	5
3	Low temperature flip-chip process using ICA and NCA (isotropically and non-conductive adhesive) for flexible displays application		4
2	Reduced temperature flip-chip technologies on flexible display substrates using adhesives		2
1	Electronics Development for Integration		137-158